

PATENT CLAIMS

1. Assembly supported on a base forming a radiator or capable of being mounted on such a base, comprising
5 a printed circuit card (1) which has in its thickness a plurality of holes (5) intended to transfer heat between one face of the said printed circuit card (1), which supports one or more electronic components (2) each enclosed by a box, and the base (3) forming a
10 radiator, having a plurality of pads (4a) which are made of a thermally conductive material and pass through the printed circuit card (1) over substantially its whole thickness while being housed by the holes (5) therein, in order to transfer heat between one face of
15 the printed circuit card (1), which supports one or more components (2), and the base, the pads (4a) are integral with a plate (4), referred to as the sole plate, which supports them, characterized in that the sole plate (4) is interposed between the printed
20 circuit card (1) and the base.
2. Assembly according to Claim 1, characterized in that the sole plate (4) is made of the same material as the bottom of the box of components (2) or of a material with similar coefficient of expansion and/or
25 electrical conductivity.
3. Assembly according to Claim 1, characterized in that it has a ductile thermal joint (6) through which it is in contact with the base (3).
4. Assembly according to Claim 2, characterized
30 in that pads are directly supported by the box of electronic components (2) and are in contact with the base (3) through a ductile joint (6).
5. Assembly according to Claim 1, characterized in that the sole plate (4) has complementary means
35 capable of mechanically holding it to the card (1).
6. Assembly according to Claim 5, characterized in that the complementary holding means are spikes (4b) which are supported by the sole plate (4) and are

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force-fitted into holes in the printed circuit card (1).

7. Assembly according to Claim 1, characterized in that the sole plate (4) and the pads (4a) are
5 soldered to the printed circuit card (1) in order to spread the thermal dissipation.

8. Assembly according to Claims 1 and 7 taken in combination, characterized in that the sole plate (4)
has through-holes (4c) for discharging the residual air
10 possibly trapped in the solder.

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